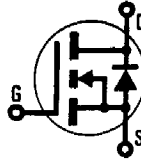


**N-CHANNEL  
 POWER MOSFETs**



**2N6788**

**Absolute Maximum Ratings**

Parameter	2N6788	Units
V <sub>DS</sub> Drain - Source Voltage (1)	100*	V
V <sub>DGR</sub> Drain - Gate Voltage (R <sub>GS</sub> = 20 KΩ) (1)	100*	V
I <sub>D</sub> @ T <sub>C</sub> = 25°C Continuous Drain Current	6.0*	A
I <sub>D</sub> @ T <sub>C</sub> = 100°C Continuous Drain Current	3.5*	A
I <sub>DM</sub> Pulsed Drain Current (3)	24*	A
V <sub>GS</sub> Gate - Source Voltage	±20*	V
I <sub>S</sub> Continuous Source Current (Body Diode)	6.0*	A
I <sub>SM</sub> Pulse Source Current (Body Diode) (3)	24*	A
P <sub>D</sub> @ T <sub>C</sub> = 25°C Max. Power Dissipation	20* (See Fig. 14)	W
Linear Derating Factor	0.16* (See Fig. 14)	WK
I <sub>LM</sub> Inductive Current, Clamped	L = 100μH 24	A
T <sub>J</sub> Operating Junction and Storage Temperature Range	-55° to 150°	°C
T <sub>lgg</sub> Lead Temperature	300* (0.063 in. (1.6mm) from case for 10s)	°C

**Electrical Characteristics @ T<sub>C</sub> = 25°C (Unless Otherwise Specified)**

Parameter	Min.	Typ.	Max.	Units	Test Conditions
BV <sub>DSS</sub> Drain - Source Breakdown Voltage	100*	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 0.25 mA
V <sub>GS(th)</sub> Gate Threshold Voltage	2.0*	—	4.0*	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 1.0 mA
I <sub>GSS</sub> Gate - Source Leakage Forward	—	—	100*	nA	V <sub>GS</sub> = 20V, V <sub>DS</sub> = 0V
I <sub>GSS</sub> Gate - Source Leakage Reverse	—	—	100*	nA	V <sub>GS</sub> = -20V, V <sub>DS</sub> = 0V
I <sub>DSS</sub> Zero Gate Voltage Drain Current	—	—	250*	μA	V <sub>DS</sub> = 100V, V <sub>GS</sub> = 0V
V <sub>DS(on)</sub> On-State Voltage (2)	—	—	2.10*	V	V <sub>GS</sub> = 10V, I <sub>D</sub> = 6.0A
R <sub>DSON</sub> Static Drain-Source On-State Resistance (2)	—	0.25	0.30*	Ω	V <sub>GS</sub> = 10V, I <sub>D</sub> = 3.5A, T <sub>A</sub> = 25°C
V <sub>SD</sub> Diode Forward Voltage (2)	0.8*	—	1.8*	V	T <sub>C</sub> = 25°C, I <sub>S</sub> = 6.0A, V <sub>GS</sub> = 0V
g <sub>fs</sub> Forward Transconductance (2)	1.5*	2.9	4.5*	S/Ω	V <sub>DS</sub> = 6V, I <sub>D</sub> = 3.5A
C <sub>iss</sub> Input Capacitance	200*	450	600*	pF	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 25V, f = 1.0 MHz
C <sub>oss</sub> Output Capacitance	100*	200	400*	pF	See Fig. 10
C <sub>rss</sub> Reverse Transfer Capacitance	20*	50	100*	pF	
t <sub>d(on)</sub> Turn-On Delay Time	—	—	40*	ns	V <sub>DD</sub> = 35V, I <sub>D</sub> = 3.5A, Z <sub>θ</sub> = 500
t <sub>r</sub> Rise Time	—	—	70*	ns	See Fig. 15
t <sub>d(off)</sub> Turn-Off Delay Time	—	—	40*	ns	(MOSFET switching times are essentially independent of operating temperature.)
t <sub>f</sub> Fall Time	—	—	70*	ns	
SOA Safe Operating Area	20	—	—	W	V <sub>DS</sub> = 80V, I <sub>D</sub> = 250 mA, See Fig. 16.
	20	—	—	W	V <sub>DS</sub> = 3.3V, I <sub>D</sub> = 60A, See Fig. 16.

**Thermal Resistance**

R <sub>thJC</sub> Junction-to-Case	—	—	6.25*	K/W	
R <sub>thJA</sub> Junction-to-Ambient	—	—	175	K/W	Free Air Operation

**Source-Drain Diode Switching Characteristics (Typical)**

t <sub>rr</sub> Reverse Recovery Time	230	ns	T <sub>J</sub> = 150°C, I <sub>F</sub> = 6.0A, di <sub>F</sub> /dt = 100A/μs
Q <sub>RR</sub> Reverse Recovered Charge	1.2	μC	T <sub>J</sub> = 150°C, I <sub>F</sub> = 6.0A, di <sub>F</sub> /dt = 100A/μs
t <sub>on</sub> Forward Turn-on Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by L <sub>S</sub> + L <sub>D</sub> .		

- ① T<sub>J</sub> = 25°C to 150°C.    ② Pulse Test: Pulse width < 300μs, Duty Cycle < 2%.    ③ Repetitive Rating: Pulse width limited by max. junction temperature.

